

TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOSⅢ)

TPCA8102

Lithium Ion Battery Applications

Notebook PC Applications

Portable Equipment Applications

- Small footprint due to small and thin package
- Low drain-source ON resistance: $R_{DS(ON)} = 4.5m\Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 60S$ (typ.)
- Low leakage current: $I_{DSS} = -10 \mu A$ (max) ($V_{DS} = -30 V$)
- Enhancement mode: $V_{th} = -0.8$ to $-2.0 V$ ($V_{DS} = -10 V$, $I_D = -1 mA$)

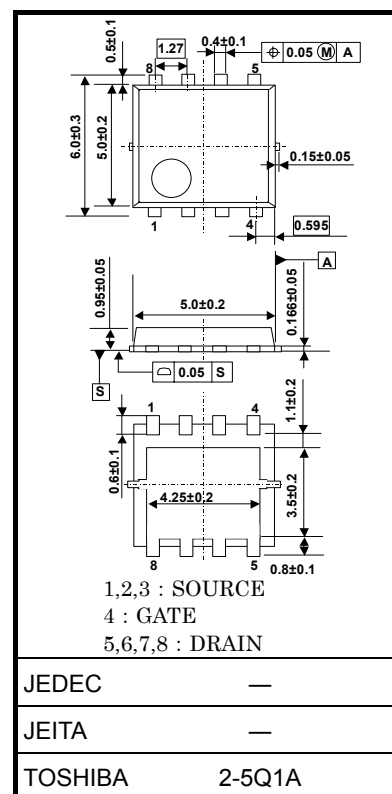
Maximum Ratings ($T_a = 25^\circ C$)

Characteristics	Symbol	Rating	Unit
Drain-source voltage	V_{DSS}	-30	V
Drain-gate voltage ($R_{GS} = 20 k\Omega$)	V_{DGR}	-30	V
Gate-source voltage	V_{GSS}	± 20	V
Drain current	DC (Note 1)	I_D	A
	Pulsed (Note 1)	I_{DP}	
Drain power dissipation ($T_c = 25^\circ C$)	P_D	45	W
Drain power dissipation ($t = 10 s$) (Note 2a)	P_D	2.8	W
Drain power dissipation ($t = 10 s$) (Note 2b)	P_D	1.6	W
Single pulse avalanche energy (Note 3)	E_{AS}	208	mJ
Avalanche current	I_{AR}	-40	A
Repetitive avalanche energy ($T_c = 25^\circ C$) (Note 4)	E_{AR}	4.5	mJ
Channel temperature	T_{ch}	150	$^\circ C$
Storage temperature range	T_{stg}	-55 to 150	$^\circ C$

Note: For (Note 1), (Note 2), (Note 3), (Note 4), please refer to the next page.

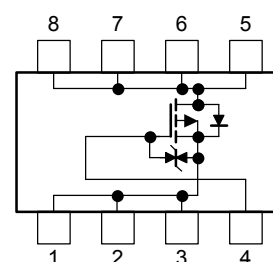
This transistor is an electrostatic sensitive device. Please handle with caution.

Unit: mm



Weight: 0.076 g (typ.)

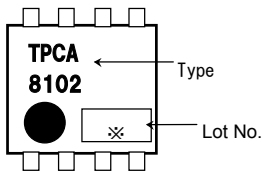
Circuit Configuration



Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case (Tc=25°C)	R _{th} (ch-c)	2.78	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R _{th} (ch-a)	44.6	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R _{th} (ch-a)	78.1	°C/W

Marking (Note 5)



Note 1: Please use devices on condition that the channel temperature is below 150°C.

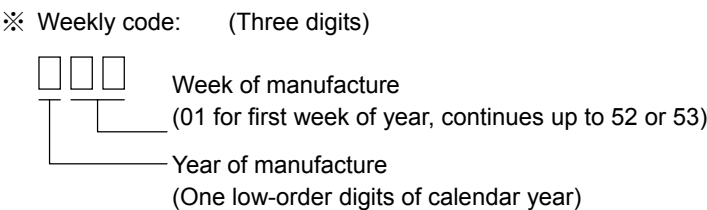
Note 2: (a) Device mounted on a glass-epoxy board (a) (b) Device mounted on a glass-epoxy board (b)



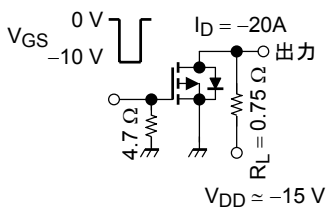
Note 3: V_{DD} = 24 V, T_{ch} = 25°C (initial), L = 100 μH, R_G = 25 Ω, I_{AR} = - 40 A

Note 4: Repetitive rating: pulse width limited by max channel temperature

Note 5: • on lower left of the marking indicates Pin 1.



Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	—	—	±10	μA
Drain cut-OFF current		I _{DSS}	V _{DS} = -30 V, V _{GS} = 0 V	—	—	-10	μA
Drain-source breakdown voltage		V _(BR) DSS	I _D = -10 mA, V _{GS} = 0 V	-30	—	—	V
		V _(BR) DSX	I _D = -10 mA, V _{GS} = 20 V	-15	—	—	
Gate threshold voltage		V _{th}	V _{DS} = -10 V, I _D = - 1 mA	-0.8	—	-2.0	V
Drain-source ON resistance		R _{DS} (ON)	V _{GS} = -4 V, I _D = -20 A	—	9.0	14	mΩ
			V _{GS} = -10 V, I _D = -20 A	—	4.5	6.0	
Forward transfer admittance		Y _{fs}	V _{DS} = -10 V, I _D = -20 A	30	60	—	S
Input capacitance		C _{iss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz	—	4600	—	pF
Reverse transfer capacitance		C _{rss}		—	850	—	
Output capacitance		C _{oss}		—	980	—	
Switching time	Rise time	t _r		—	10	—	ns
	Turn-ON time	t _{on}		—	20	—	
	Fall time	t _f		—	78	—	
	Turn-OFF time	t _{off}		—	220	—	
Total gate charge (gate-source plus gate-drain)		Q _g	V _{DD} ≈ -24 V, V _{GS} = 10 V, I _D = -40 A	—	109	—	nC
Gate-source charge 1		Q _{gs1}		—	24	—	
Gate-drain (“miller”) charge		Q _{gd}		—	25	—	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Drain reverse current	Pulse (Note 1)	I_{DRP}	—	—	—	-120	A
Forward voltage (diode)		V_{DSF}	$I_{DR} = -40 \text{ A}, V_{GS} = 0 \text{ V}$	—	—	1.2	V

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